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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	6.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	512
Number of Gates	-
Number of I/O	256
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	352-LBGA
Supplier Device Package	352-SBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5lv-512-256-6sac

Table 2. MACH 5 Speed Grades

Device	Speed Grade ¹						
	-5	-6	-7	-10	-12	-15	-20
M5-128 ²			C	C, I	C, I	C, I	I
M5-128/1	C		C, I	C, I	C, I	C, I	I
M5LV-128	C		C, I	C, I	C, I	I	
M5-192/1	C		C, I	C, I	C, I	C, I	I
M5-256 ²			C	C, I	C, I	C, I	I
M5-256/1	C		C, I	C, I	C, I	C, I	I
M5LV-256	C		C, I	C, I	C, I	I	
M5-320		C	C, I	C, I	C, I	C, I	I
M5LV-320		C	C, I	C, I	C, I	C, I	I
M5-384		C	C, I	C, I	C, I	C, I	I
M5LV-384		C	C, I	C, I	C, I	C, I	I
M5-512		C	C, I	C, I	C, I	C, I	I
M5LV-512		C	C, I	C, I	C, I	C, I	I

Note:

1. C = Commercial grade, I = Industrial grade
2. /1 version recommended for new designs

With Lattice's unique hierarchical architecture, the MACH 5 family provides densities up to 512 macrocells to support full system logic integration. Extensive routing resources ensure pinout retention as well as high utilization. It is ideal for PAL[®] block device integration and a wide range of other applications including high-speed computing, low-power applications, communications, and embedded control. At each macrocell density point, Lattice offers several I/O and package options to meet a wide range of design needs (Table 3).

Table 3. MACH 5 Package and I/O Options ¹

Supply Voltage	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
	5	3.3		5	3.3	5	3.3	5	3.3	5	3.3
100-pin TQFP	68	68, 74	68	68	68*, 74						
100-pin PQFP	68	68*	68*	68*	68						
144-pin TQFP		104			104						
144-pin PQFP	104	104*	104*	104*	104*						
160-pin PQFP	120	120	120	120	120	120*	120	120*	120	120*	120
208-pin PQFP				160	160	160	160	160	160	160	160
240-pin PQFP						184*	184*	184*	184*	184*	184*
256-ball BGA						192	192*	192*	192*	192*	192*
352-ball BGA										256	256

Note:

1. The I/O options indicated with a "*" are obsolete, please contact factory for more information.

Advanced power management options allow designers to incrementally reduce power while maintaining the level of performance needed for today's complex designs. I/O safety features allow for mixed-voltage design,

Select devices have been discontinued.
See Ordering Information section for product status.

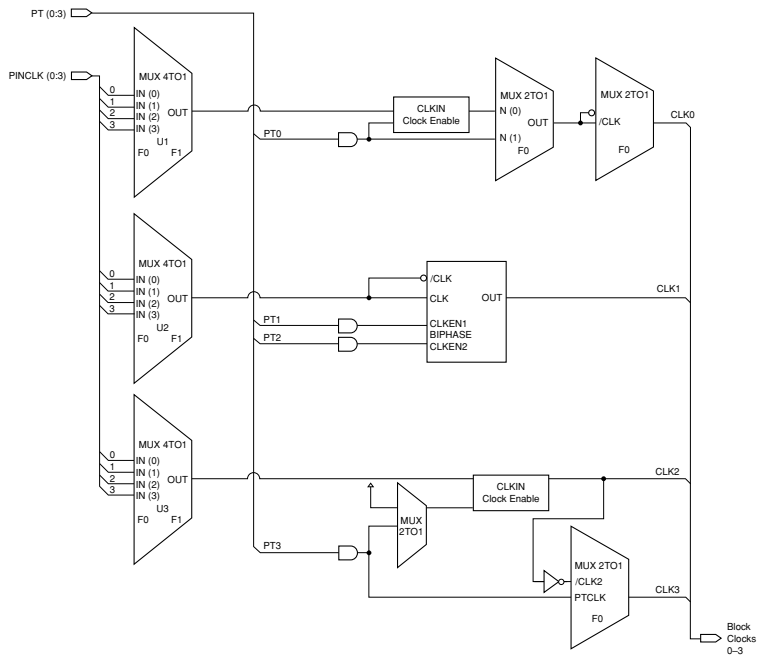
- ◆ Global clock (0, 1, 2, or 3) with positive and negative edge clock enable (biphase)

Clock Line 2 Options

- ◆ Global clock (0, 1, 2, or 3) with clock enable

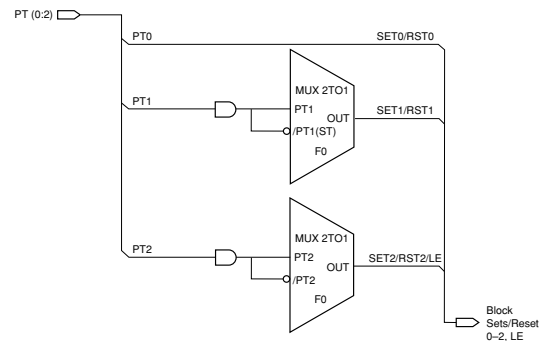
Clock Line 3 Options

- ◆ Complement of clock line 2 (same clock enable)
- ◆ Product-term clock (if clock line 2 does not use clock enable)



20446G-004

Figure 4. Clock Generator



20446G-005

Figure 5. Set/Reset Generator

The set/reset generation portion of the control generator (Figure 5) creates three set/reset lines for the PAL block. Each macrocell can choose one of these three lines or choose no set/reset at all. All three lines can be configured for product term set/reset and two of the three lines can be configured as sum term set/reset and one of the lines can be configured as product-term or sum-term latch enable. While the set/reset signals are generated in the control generator, whether that signal sets or resets a flip-flop is determined within the individual macrocell. The same signal can set one flip-flop and reset another. PT2 or /PT2 can also be used as a latch enable for macrocells configured as latches.

**Select devices have been discontinued.
See Ordering Information section for product status.**

OE Generator

There is one output enable (OE) generator per PAL block that generates two product-term driven output enables. Each I/O cell is simply an output buffer. Each I/O cell within the PAL block can choose to be permanently enabled, permanently disabled, or choose one of the two product term output enables per PAL block (Figure 6).

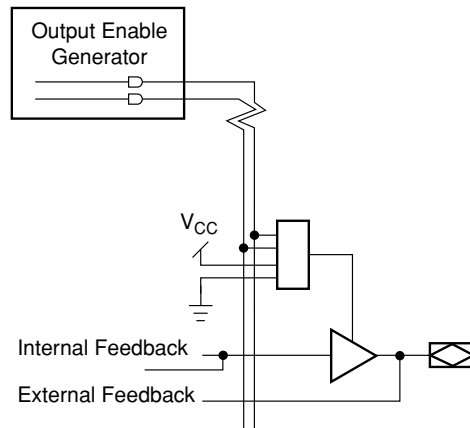


Figure 6. Output Enable Generator and I/O Cell

20446G-006

Select devices have been discontinued.
See Ordering Information section for product status.



MULTIPLE I/O AND DENSITY OPTIONS

The MACH 5 family offers six macrocell densities in a number of I/O options. This allows designers to choose a device close to their logic density and I/O requirements, thus minimizing costs. For the same package type, every density has the same pin-out. With proper design considerations, a design can be moved to a higher or lower density part as required.

IEEE 1149.1 - COMPLIANT BOUNDARY SCAN TESTABILITY

Most MACH 5 devices have boundary scan registers and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1 - COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All MACH 5 devices provide in-system programming (ISP) capability through their IEEE 1149.1-compliant Boundary Scan Test Access Port. By using the IEEE 1149.1-compliant Boundary Scan Test Access Port as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

MACH 5 devices can be programmed across the commercial temperature and voltage range. The PC-based LatticePRO software facilitates in-system programming of MACH 5 devices. LatticePRO software takes the JEDEC file output produced by design implementation software, along with information about the Boundary Scan chain, and creates a set of vectors that are used to drive the Boundary Scan chain. LatticePRO software can use these vectors to drive a Boundary Scan chain via the parallel port of a PC. Alternatively, LatticePRO software can output files in formats understood by common automated test equipment. This equipment can then be used to program MACH 5 devices during the testing of a circuit board.

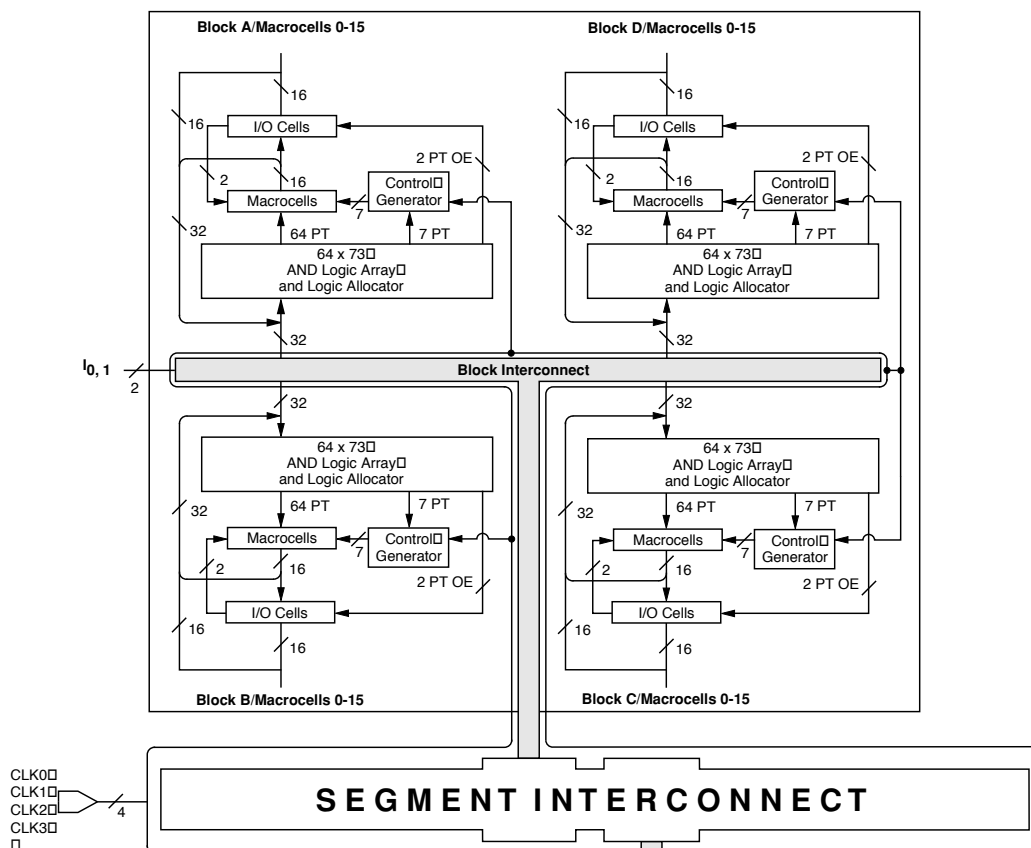
PCI COMPLIANT

MACH 5 devices in the -5/-6/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature. MACH 5 devices provide the speed, drive, density, output enables and I/Os for the most complex PCI designs.

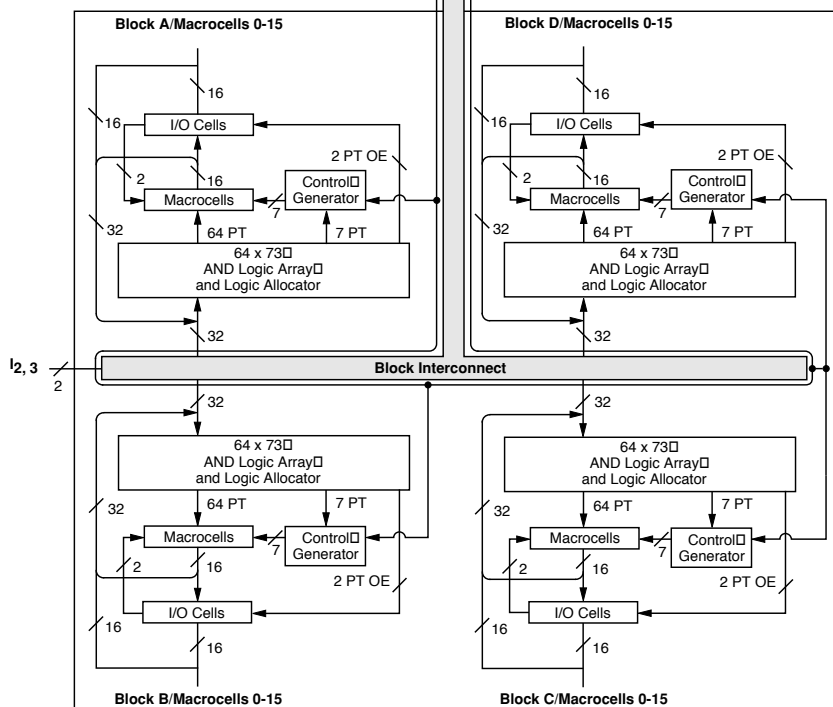
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BLOCK DIAGRAM — M5(LV)-128/XXX

SEGMENT 0



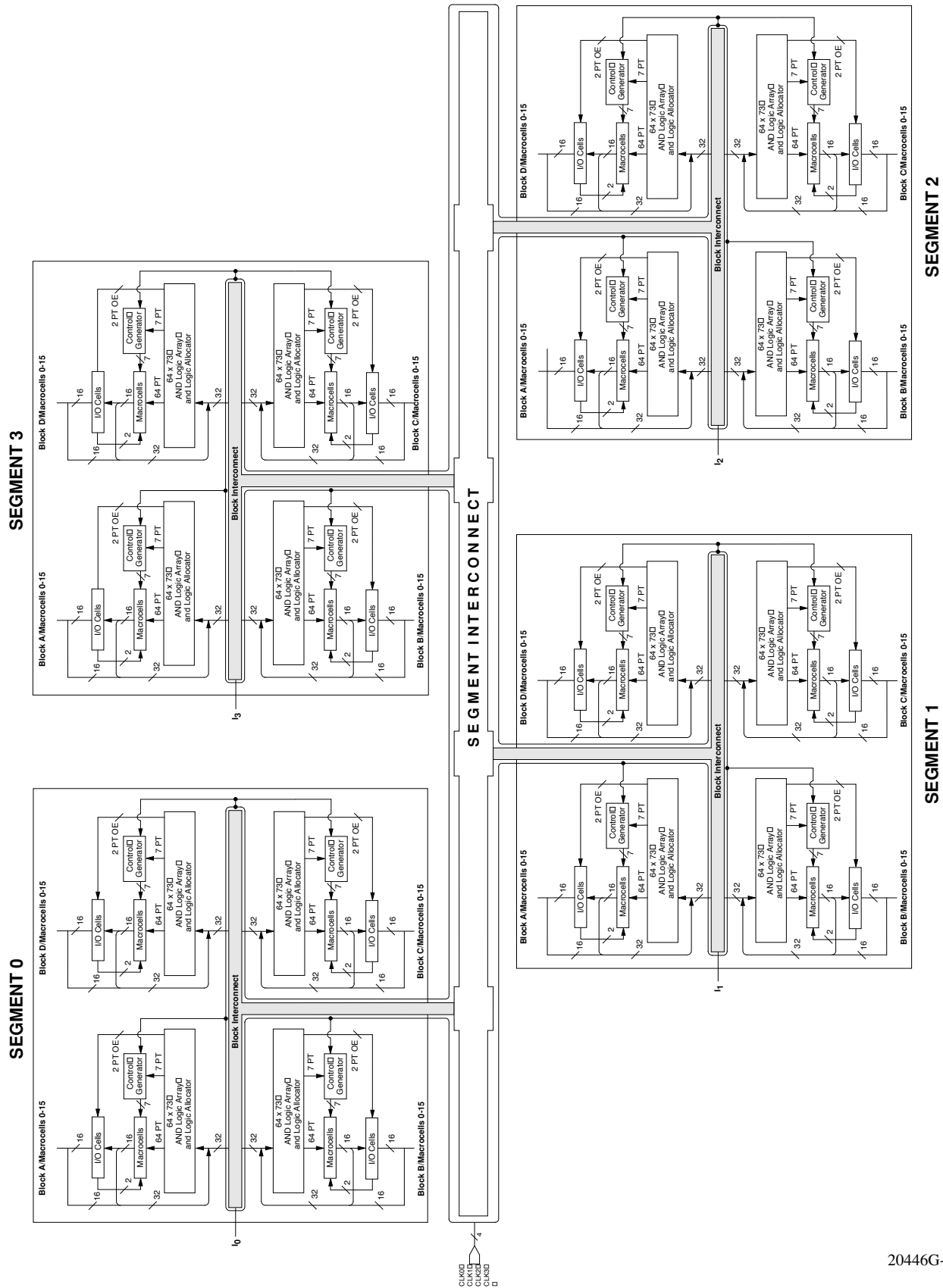
SEGMENT 1



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20446G-007

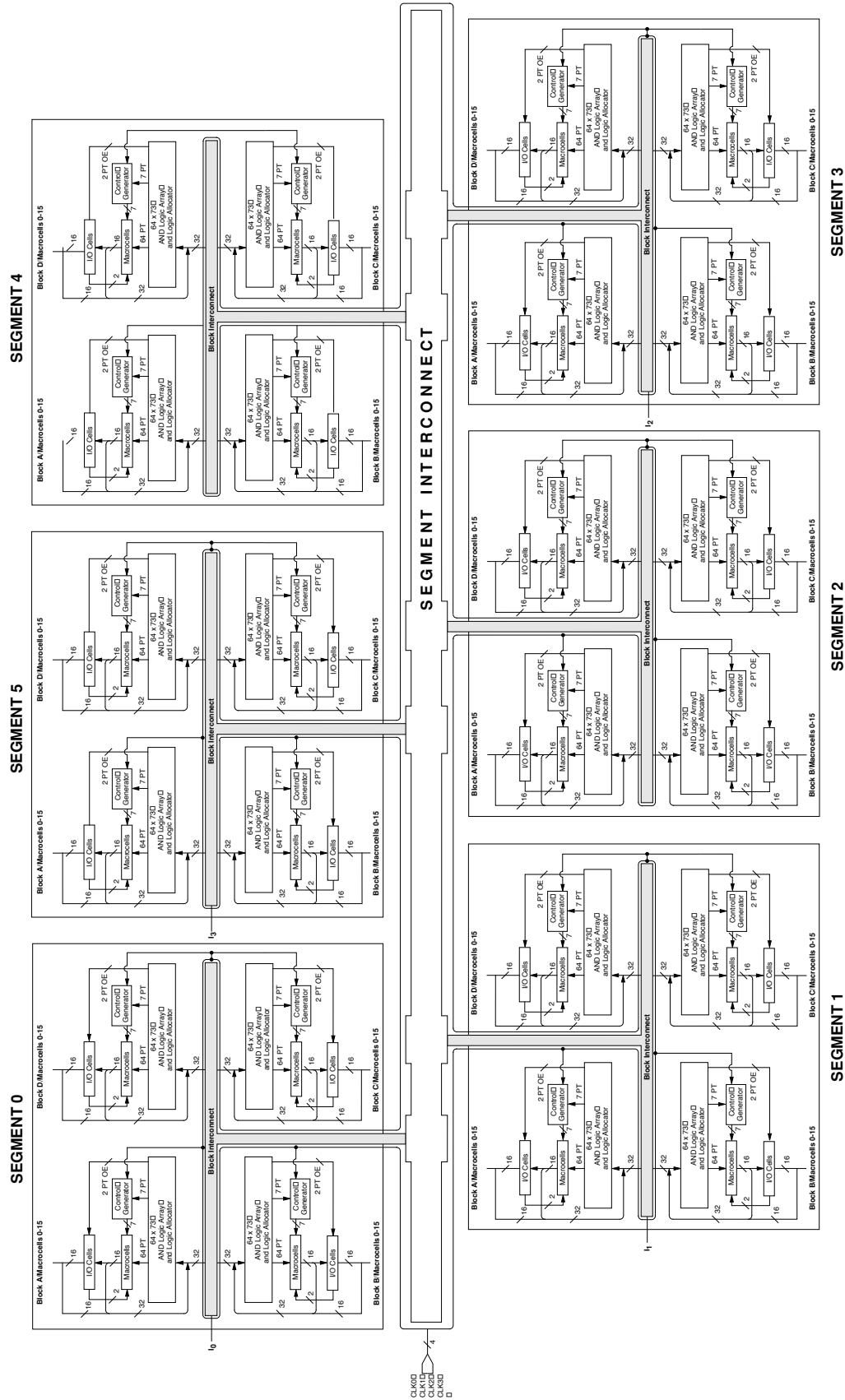
BLOCK DIAGRAM — M5(LV)-256/XXX



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-009

BLOCK DIAGRAM — M5(LV)-384/XXX



20446G-011

Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5LV

Storage Temperature. -65°C to +150°C
Device Junction Temperature. +130°C
Supply Voltage
with Respect to Ground. -0.5 V to +4.5 V
DC Input Voltage. -0.5 V to 5.5 V
Static Discharge Voltage. 2000 V
Latchup Current (-40°C to +85°C). 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air. 0°C to +70°C
Supply Voltage (V_{CC})
with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air. -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground. +3.0 V to +3.6 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

Select devices have been discontinued.
See Ordering Information section for product status.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description		Min	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$	$I_{OH} = -100 \mu A$	$V_{CC} - 0.2$		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = 3.2 \text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 100 \mu A$		0.2	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 16 \text{ mA (Note 1)}$		0.5	V
V_{IH}	Input HIGH Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		2.0	5.5	V
V_{IL}	Input LOW Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		-0.3	0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6, V_{CC} = \text{Max (Note 3)}$			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max (Note 3)}$			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 4)}$		-15	-160	mA

Notes:

1. Total I_{OL} between ground pins should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
4. Not more than one output should be shorted at one time. Duration of the short-circuit should not exceed one second.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Combinatorial Delay:																
t _{PDi}	Internal combinatorial propagation delay		3.5		4.5		5.5		8.0		10.0		13.0		18.0	ns
t _{PD}	Combinatorial propagation delay		5.5		6.5		7.5		10.0		12.0		15.0		20.0	ns
Registered Delays:																
t _{SS}	Synchronous clock setup time	3.0		3.0		4.0		5.0		6.0		8.0		10.0		ns
t _{SA}	Asynchronous clock setup time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HA}	Asynchronous clock hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{COsi}	Synchronous clock to internal output		2.5		3.0		4.0		5.0		6.0		8.0		10.0	ns
t _{COS}	Synchronous clock to output		4.5		5.0		6.0		7.0		8.0		10.0		12.0	ns
t _{COAi}	Asynchronous clock to internal output		6.0		6.0		8.0		10.0		13.0		15.0		18.0	ns
t _{COA}	Asynchronous clock to output		8.0		8.0		10.0		12.0		15.0		17.0		20.0	ns
Latched Delays:																
t _{SAL}	Latch setup time	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HAL}	Latch hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{PDLi}	Transparent latch internal		6.0		7.0		7.0		8.0		9.0		10.0		10.0	ns
t _{PDL}	Propagation delay through transparent latch		8.0		9.0		9.0		10.0		11.0		12.0		12.0	ns
t _{GOAi}	Gate to internal output		7.0		8.0		8.0		9.0		10.0		11.0		12.0	ns
t _{GOA}	Gate to output		9.0		10.0		10.0		11.0		12.0		13.0		14.0	ns
Input Register Delays:																
t _{SIRS}	Input register setup time using a synchronous clock	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{SIRA}	Input register setup time using an asynchronous clock	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HIRS}	Input register hold time using a synchronous clock	3.0		3.0		3.0		4.0		4.0		4.0		4.0		ns
t _{HIRA}	Input register hold time using an asynchronous clock	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
Input Latch Delays:																
t _{SIL}	Input latch setup time	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{HIL}	Input latch hold time	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
t _{PDILi}	Transparent input latch		5.0		5.0		5.5		6.0		6.0		6.0		6.0	ns
Output Delays:																
t _{BUF}	Output buffer delay		2.0		2.0		2.0		2.0		2.0		2.0		2.0	ns
t _{SLW}	Slow slew rate delay		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns
t _{ER}	Output disable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Power Delays:																
t _{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t _{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t _{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t _{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t _{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t _{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t _{SRI}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t _{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t _{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t _{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t _{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t _{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Frequency:																
f _{MAX}	External feedback, PAL block level. Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SS} + t _{COS})	133		125		100		83.3		71.4		55.6		45.5		MHz
	Internal feedback, PAL block level. Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SS} + t _{COSi})	182		167		125		100		83.3		62.5		50.0		MHz
	No feedback PAL block level. Min of 1/(t _{WLS} + t _{WHS}) or 1/(t _{SS} + t _{HS})	200		167		167		125		100		83.3		83.3		MHz
f _{MAXA}	External feedback, PAL block level. Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SA} + t _{COA})	91		91		71.4		58.8		47.6		41.7		35.7		MHz
	Internal feedback, PAL block level. Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SA} + t _{COAi})	111		111		83.3		66.7		52.6		45.5		38.5		MHz
	No feedback, PAL block level. Min of 1/(t _{WLA} + t _{WHA}) or 1/(t _{SA} + t _{HA})	167		125		125		100		83.3		71.4		62.5		MHz
f _{MAXI}	Maximum input register frequency 1/(t _{SIRS} + t _{HIRS}) or 1/(2 x t _{WICW})	167		125		125		100		83.3		71.4		62.5		MHz

Notes:

- See "MACH Switching Test Circuits" documentation on the Lattice Data Book CD-ROM or Lattice web site.
- Numbers in parentheses are for M5-128, M5-192, M5-256.
- If a signal is used as both a clock and a logic array input, then the maximum input frequency applies ($f_{MAX}/2$).

Select devices have been discontinued.
See Ordering Information section for product status.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test conditions		Typ	Unit
C_{IN}	I/CLK pin	$V_{IN} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	12	pF
$C_{I/O}$	I/O pin	$V_{OUT} = 2.0\text{ V}$	3.3 V or 5 V, 25° C, 1 MHz	10	pF

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where these parameters may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power. For a more detailed discussion about MACH 5 power consumption, refer to the application note entitled *MACH 5 Power* in the Application Notes section on the Lattice Data Book CD-ROM or Lattice web site.

I_{CC} CURVES AT HIGH /LOW POWER MODES

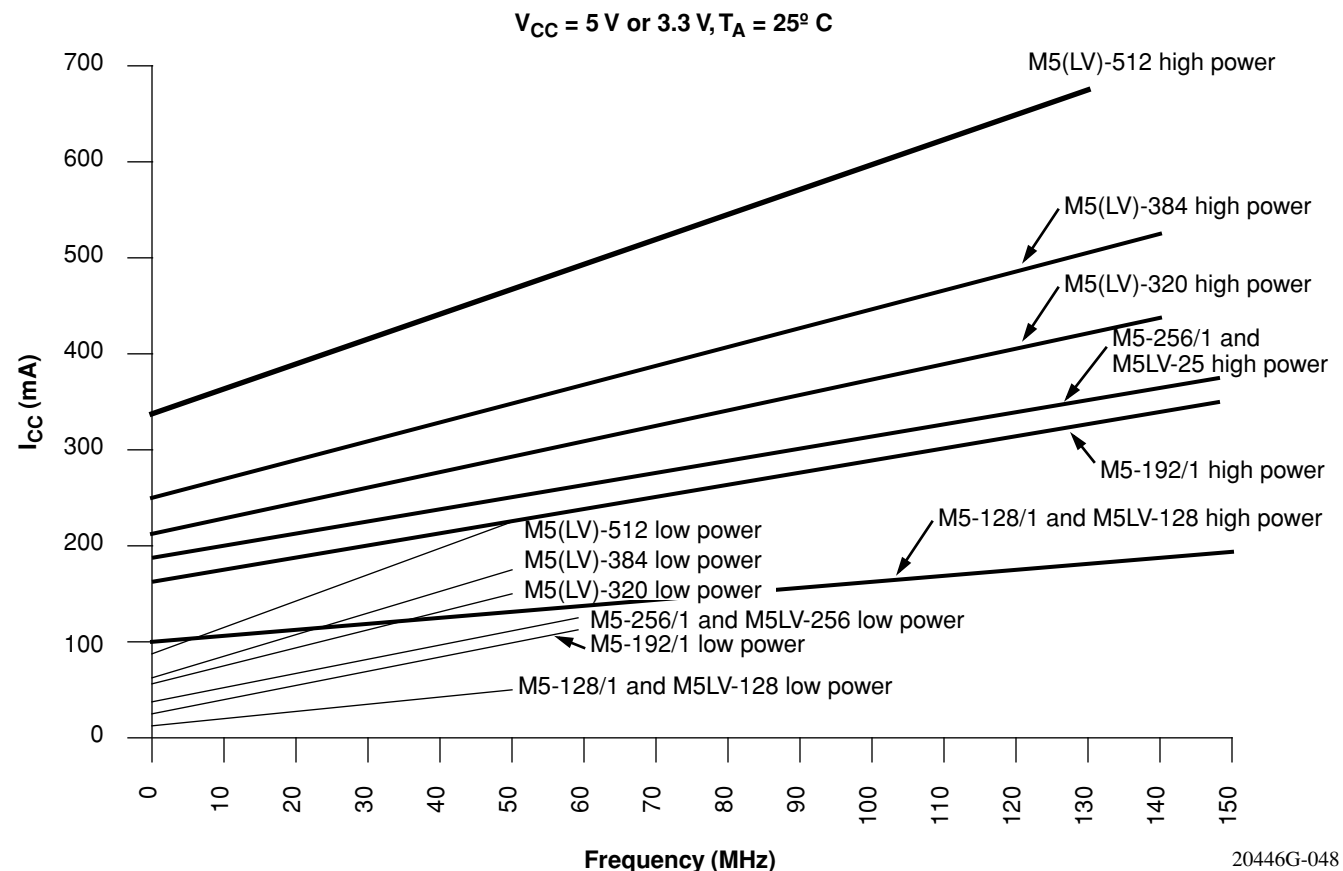


Figure 8. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued. See Ordering Information section for product status.

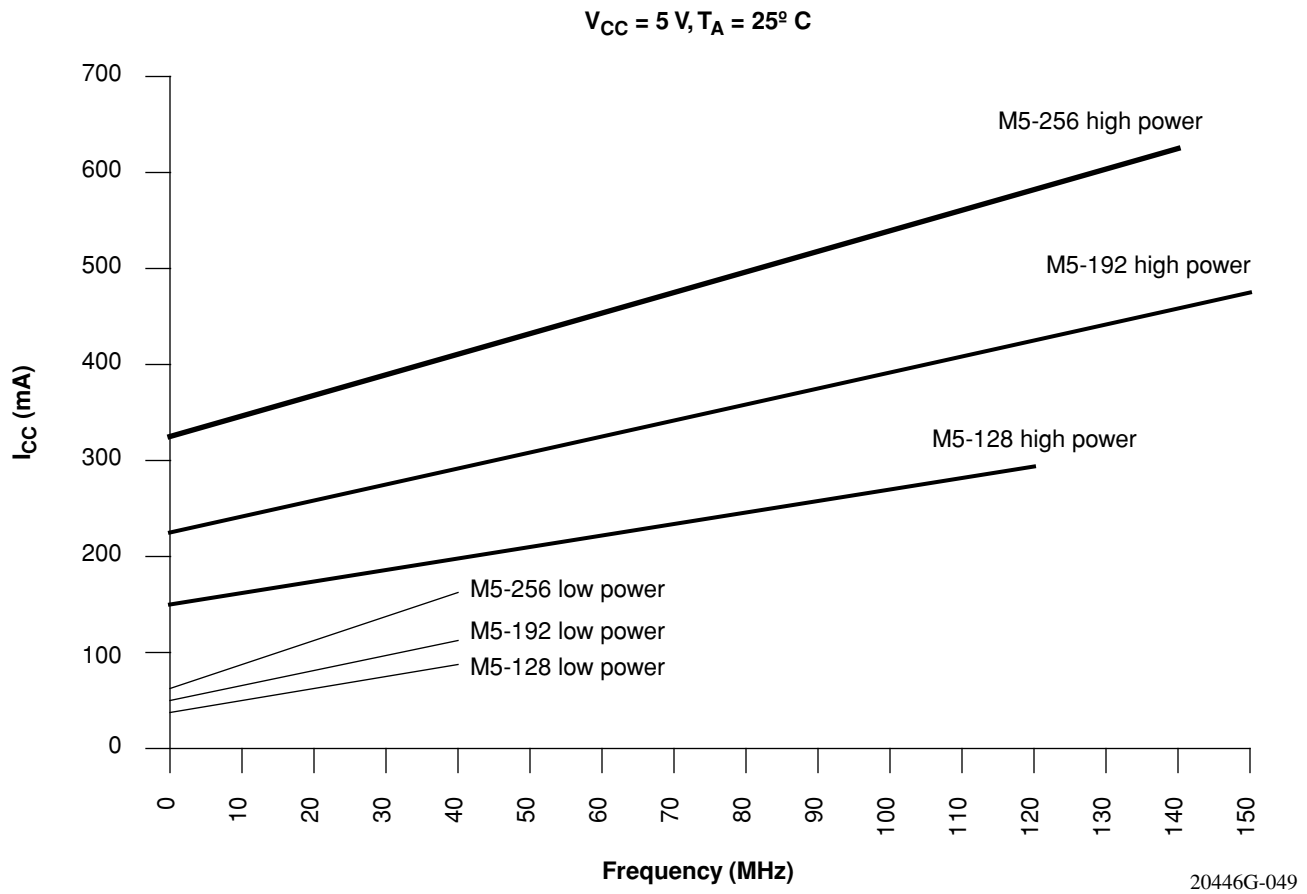


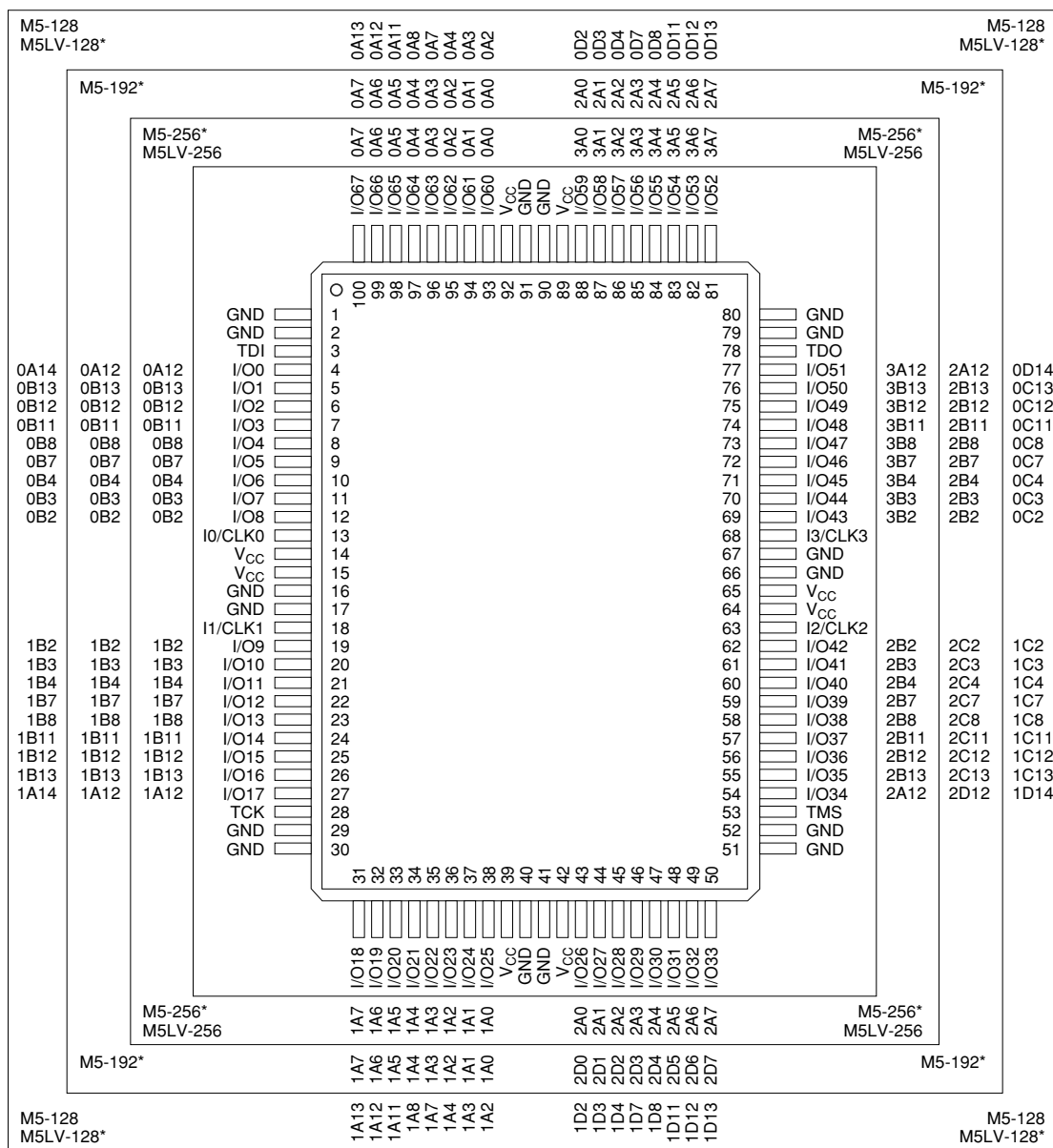
Figure 9. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued.
See Ordering Information section for product status.

100-PIN PQFP CONNECTION DIAGRAM

Top View

100-Pin PQFP (68 I/O)



*Package obsolete, contact factory.

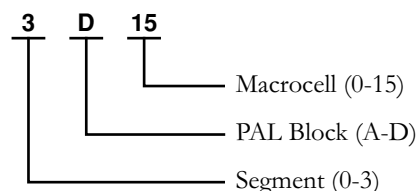
20446G-016

Select devices have been discontinued.
See Ordering Information section for product status.

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

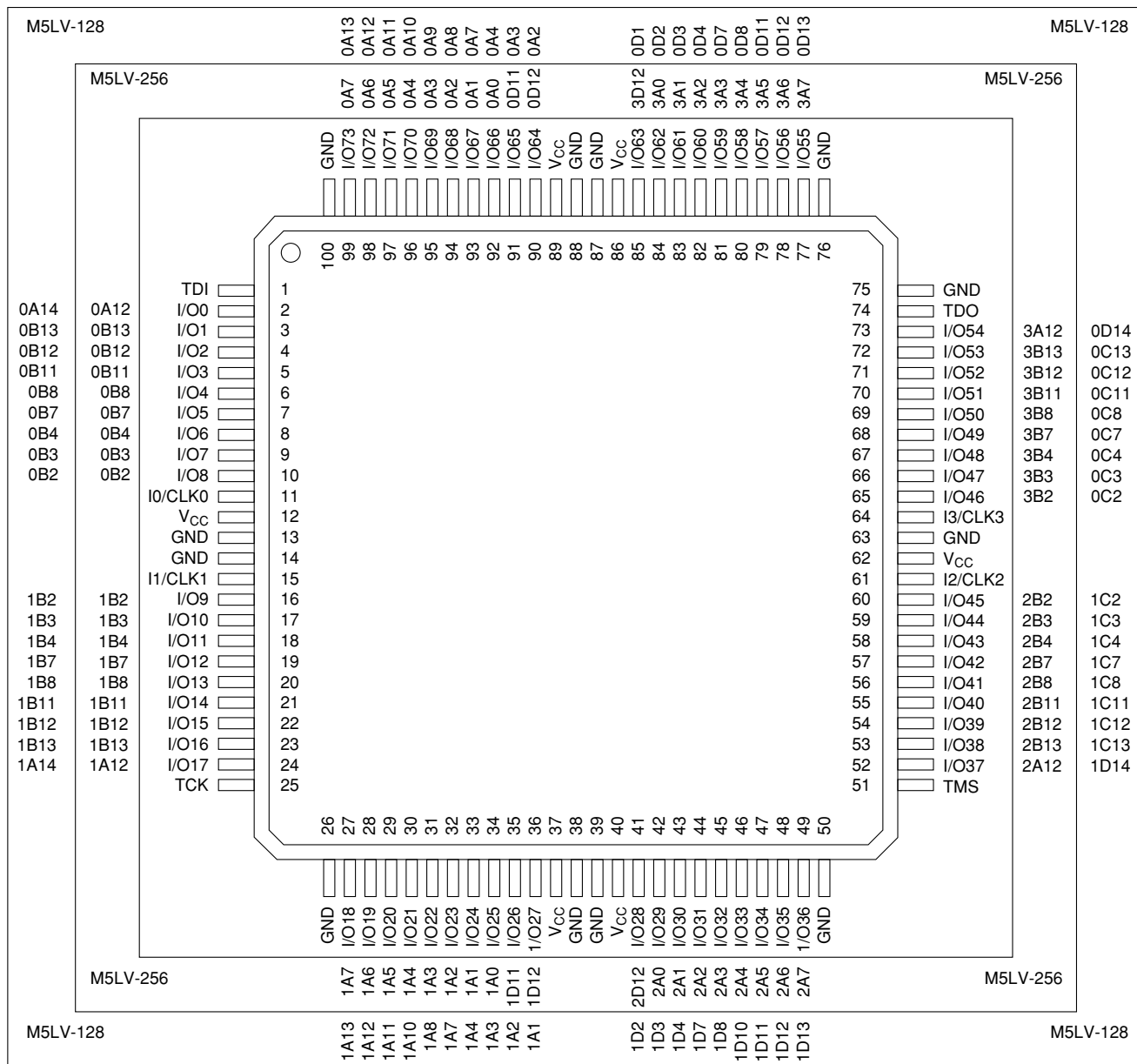
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



100-PIN TQFP CONNECTION DIAGRAM – 74 I/O

Top View

100-Pin TQFP (74 I/O)



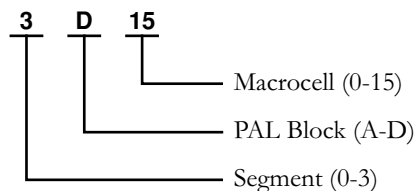
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-018

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

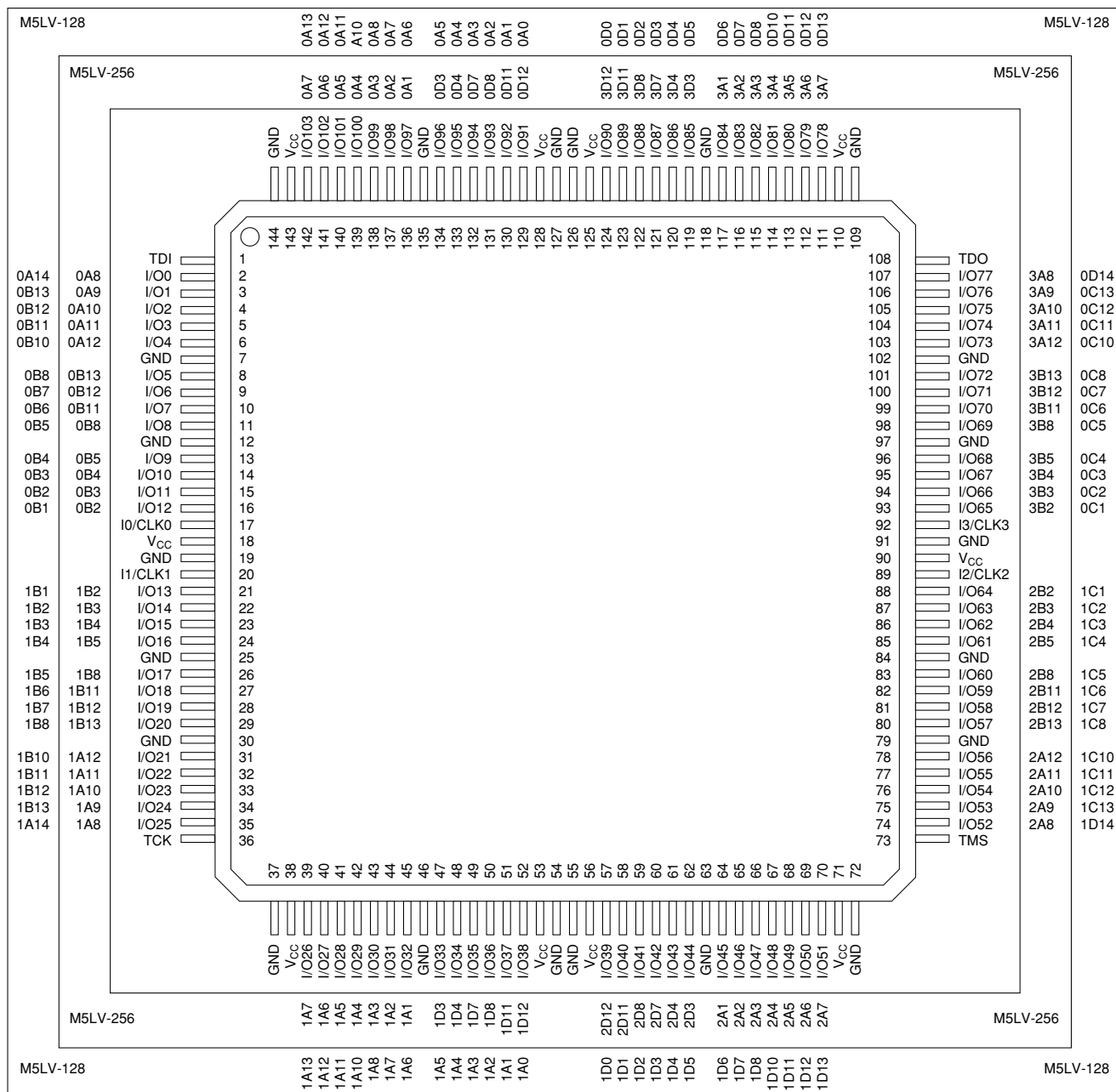
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



144-PIN TQFP CONNECTION DIAGRAM

Top View

144-Pin TQFP



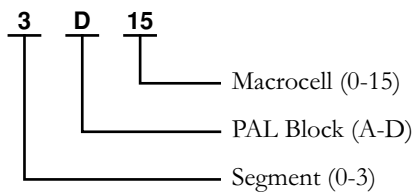
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-020

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out

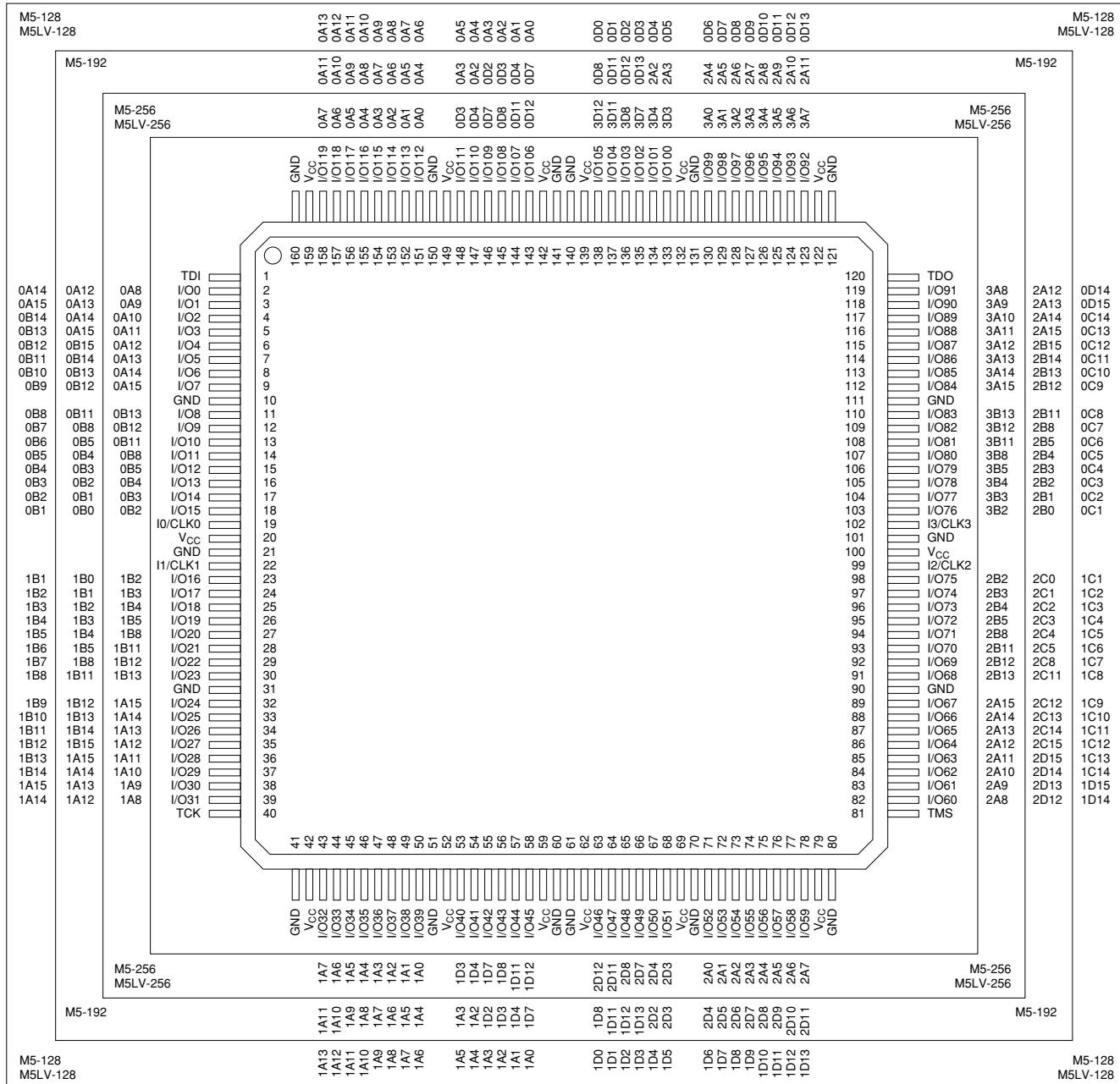


160-PIN PQFP CONNECTION DIAGRAM

Top View

160-Pin PQFP (128, 192, 256 Macrocells)

Select devices have been discontinued.
See Ordering Information section for product status.



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (Macrocell Association)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	
1	GND	GND	3A11	3D15	3D12	GND	3D7	GND	3D3	3D2	GND	2D2	GND	2D7	GND	2D10	2D13	2D15	GND	GND	1
2	GND	3B2	3A3	3A8	3A13	3D13	3D9	3D8	3D4	I3/CLK3	I2/CLK2	2D3	2D4	2D8	2D12	2A15	2A13	2A12	2A9	2A7	2
3	GND	3B8	V _{CC}	3A2	3A4	3A12	3D14	3D10	3D5	3D0	2D0	2D5	2D9	2D14	2A14	2A10	2A8	V _{CC}	2A3	GND	3
4	3B13	3B11	3B3	V _{CC}	TDO	3A7	V _{CC}	3D11	3D6	3D1	2D1	2D6	2D11	V _{CC}	2A11	TMS	V _{CC}	2A6	2A2	2A0	4
5	4B14	4B15	3B4	V _{CC}	Pin Designations CLK = Clock GND = Ground I = Input I/O = Input/Output NC = No Connect V_{CC} = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out												V _{CC}	2A5	2B0	2B1	5
6	GND	4B11	3B12	3B7													2A4	2A1	2B4	GND	6
7	4B8	4B10	4B13	V _{CC}													V _{CC}	2B2	2B5	2B7	7
8	4B4	4B6	4B9	4B12													2B3	2B6	2B9	2B11	8
9	GND	4B3	4B5	4B7													2B8	2B10	2B12	GND	9
10	GND	4B0	4B1	4B2													2B13	2B14	2B15	GND	10
11	GND	4A0	4A1	4A2													1B13	1B14	1B15	GND	11
12	GND	4A3	4A5	4A7													1B8	1B10	1B12	GND	12
13	4A4	4A6	4A9	4A12	4 D 15 Macrocell (0-15) PAL Block (A-D) Segment (0-4)												1B3	1B6	1B9	1B11	13
14	4A8	4A10	4A13	V _{CC}													V _{CC}	1B2	1B5	1B7	14
15	GND	4A11	0B12	0B7													1A4	1A1	1B4	GND	15
16	4A14	4A15	0B4	V _{CC}													V _{CC}	1A5	1B0	1B1	16
17	0B13	0B11	0B3	V _{CC}	TDI	0A7	V _{CC}	0D11	0D6	0D1	1D1	1D6	1D11	V _{CC}	1A11	TCK	V _{CC}	1A6	1A2	1A0	17
18	GND	0B8	V _{CC}	0A2	0A4	0A12	0D14	0D9	0D5	0D0	1D0	1D5	1D10	1D14	1A14	1A10	1A8	V _{CC}	1A3	GND	18
19	0B2	0A3	0A8	0A11	0A13	0D12	0D8	0D4	0D3	I0/CLK0	I1/CLK1	1D4	1D8	1D9	1D13	1A15	1A12	1A9	1A7	GND	19
20	GND	GND	0D15	0D13	0D10	GND	0D7	GND	0D2	GND	1D2	1D3	GND	1D7	GND	1D12	1D15	1A13	GND	GND	20

Select devices have been discontinued.
See Ordering Information section for product status.